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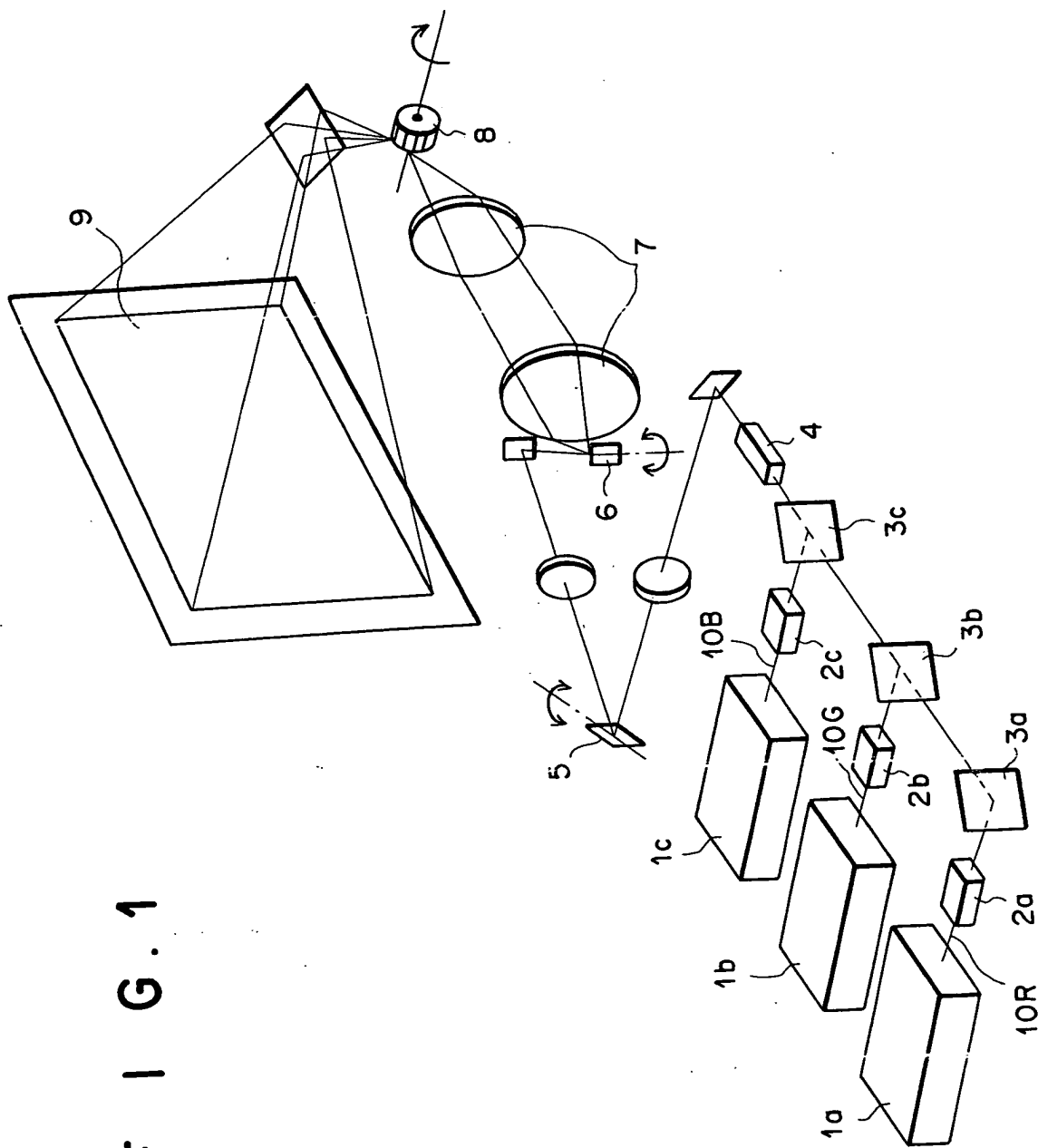
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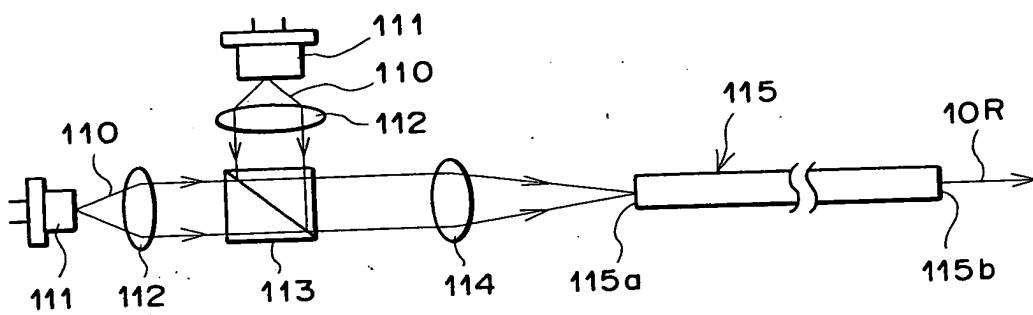
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FIG. 1

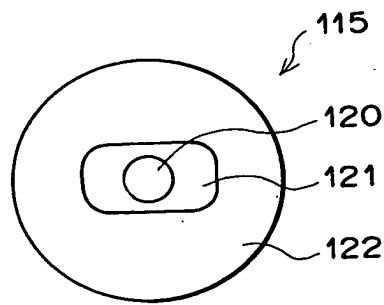


# FIG. 2

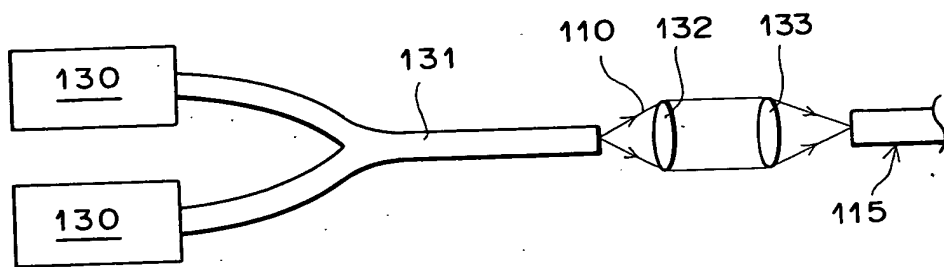
1a



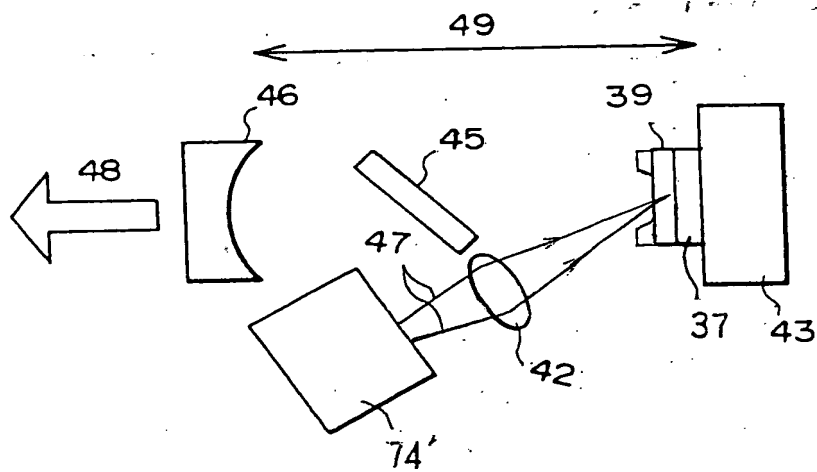
# FIG. 3



F I G . 4

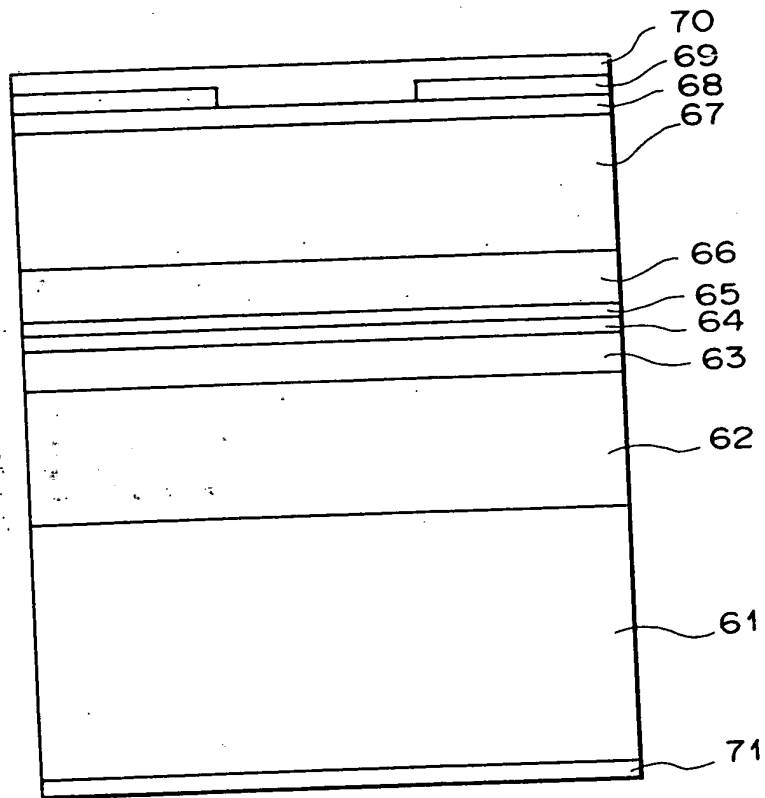


F I G . 5



# FIG. 6

74



F I G . 7

39

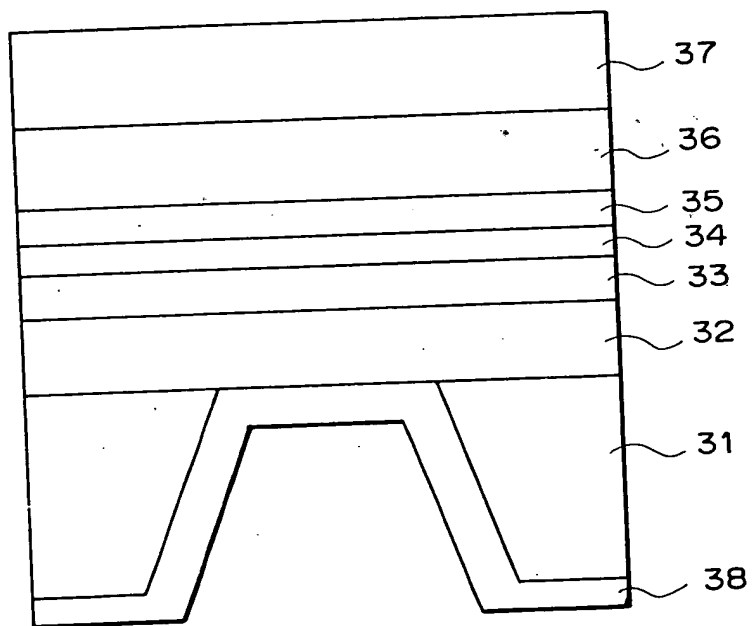




FIG. 8A is a schematic diagram of a first embodiment of a device for measuring the thickness of a substrate. The device includes a light source 108, a collimating lens 105, a beam splitter 104, a sample 81, a reference surface 89, a detector 106, and a display 74. Light from the source 108 is collimated by lens 105 and directed to the beam splitter 104. The beam splitter 104 directs the light to the sample 81 and the reference surface 89. The light reflected from the sample 81 and the reference surface 89 is directed to the detector 106, which is connected to the display 74. The distance between the beam splitter 104 and the detector 106 is indicated by the dimension line 109.

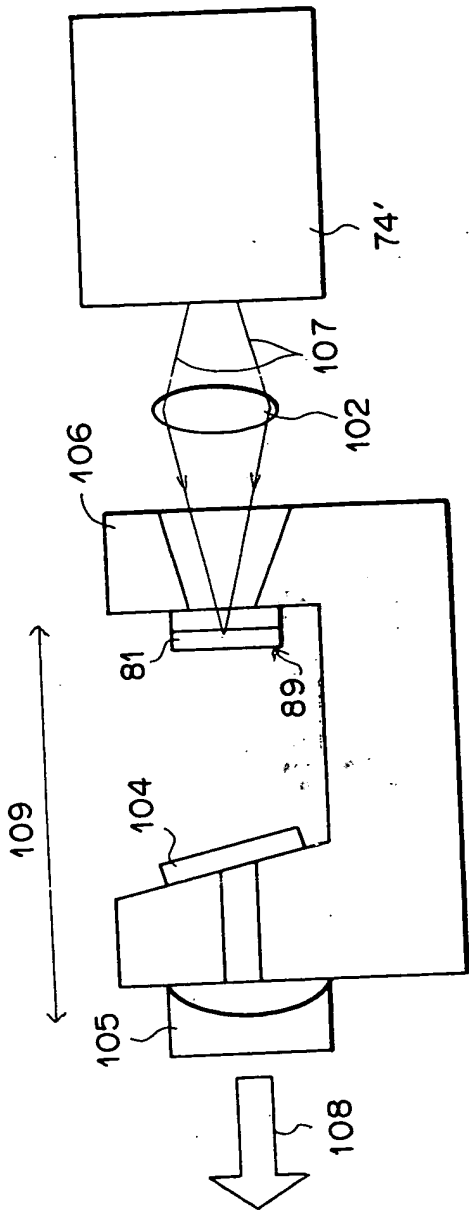
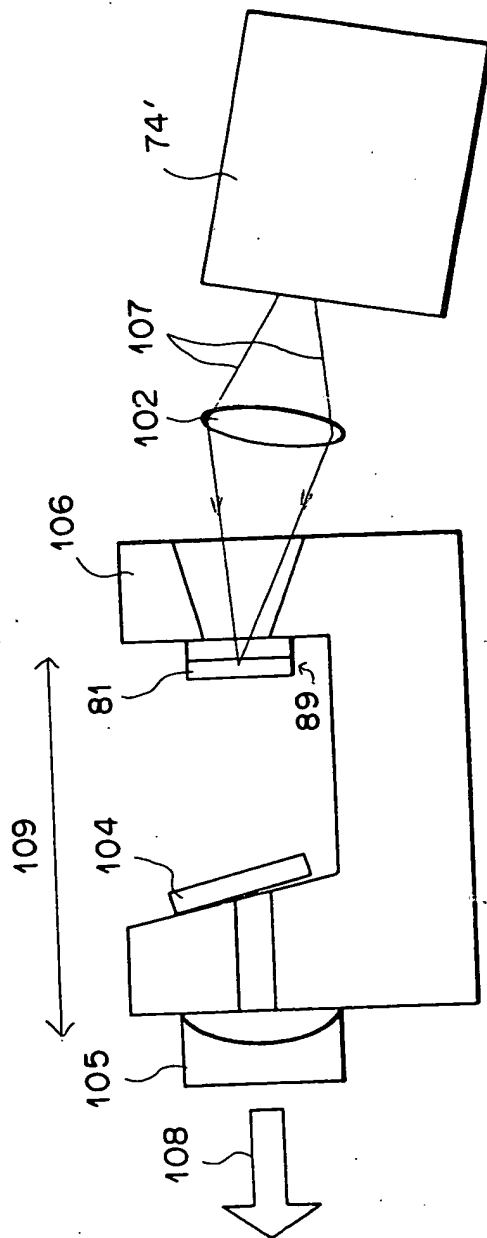


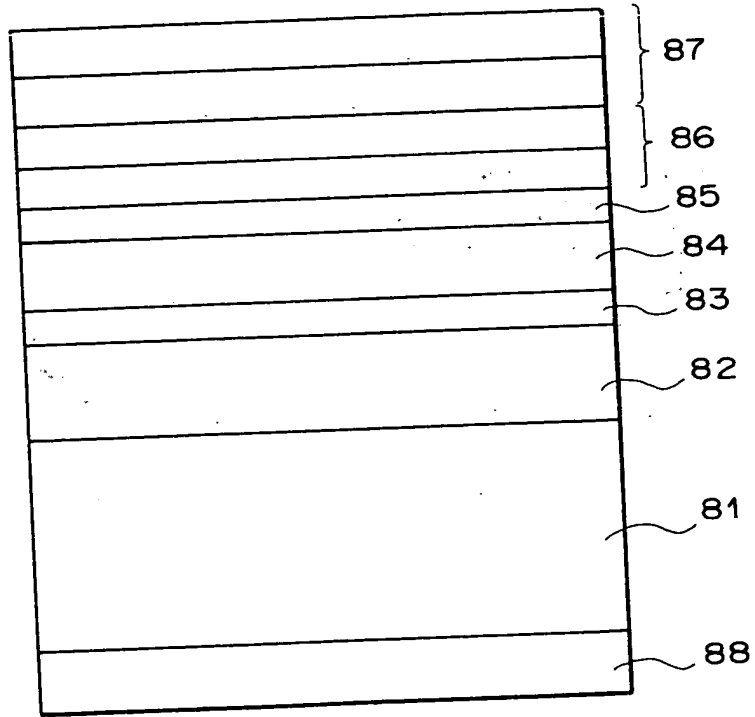
FIG. 8A

FIG. 8B



# FIG. 9

89



# F I G . 10

